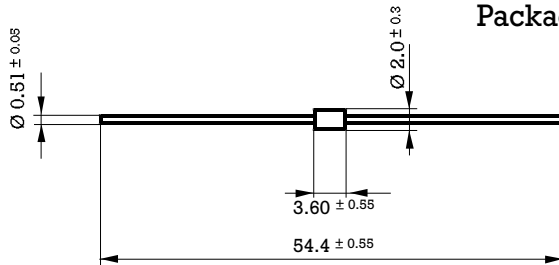


DIAC

Dimensions in mm.

DO-35
Glass Axial
Package

Mounting instructions

1. Min. distance from body to soldering point, 4 mm.
2. Max. solder temperature, 250 °C.
3. Max. soldering time, 3.5 sec.
4. Do not bend lead at a point closer than 2 mm. to the body.

- Silicon bi-directional trigger device intended for use in thyristor (SCR and TRIAC) trigger circuits, energy saving lighting circuits and other switching functions.

 BREAKOVER VOLTAGE
 32 V

 ON-STATE CURRENT
 2.0 Amps

SPECIAL FEATURES:

- Low breakover current.
- Excellent symmetry.
- Very low leakage current.

MARKING CODE

P1
Absolute Maximum Ratings, according to IEC publication No. 134

	PARAMETER	CONDITIONS	Min.	Typ.	Max.	Unit
P_{tot}	Total Power Dissipation	$T_a = 65\text{ °C}$			150	mW
I_{TRM}	Repetitive peak on-state current	$t_p = 20\text{ }\mu\text{s}$, $f = 100\text{ Hz}$			2	A
T_{stg}	Storage Temperature Range		-40		+125	°C
T_j	Operating Junction Temperature		-40		+125	°C

Thermal Resistance

	PARAMETER	CONDITIONS	Min.	Typ.	Max.	Unit
$R_{th(j-a)}$	Junction to Ambient			400		°C/W
$R_{th(j-l)}$	Junction to leads			150		°C/W

Electrical Characteristics at $T_{amb} = 25\text{ °C}$

	PARAMETER	CONDITIONS	Min.	Typ.	Max.	Unit
V_{BO}	Breakover Voltage *	I_{BO} , $C = 22\text{ nF}$ ** (see Figure 1)	28	32	36	V
$ V_{BO+} - V_{BO-} $	Breakover Voltage Symmetry	I_{BO} , $C = 22\text{ nF}$ ** (see Figure 1)			± 3	V
$ DV_{\pm} $	Dynamic breakover voltage *	$DI = [I_{BO} \text{ to } I_F = 10\text{ mA}]$ (see Figure 1)	5			V
V_O	Output Voltage *	(see Figure 3)	5			V
I_{BO}	Breakover Current *	$C = 22\text{ nF}$ **			50	μA
t_r	Rise Time *	(see Figure 4)		1.5		μs
I_B	Leakage Current *	$V_B = 0.5 V_{BO}\text{ max}$ (see Figure 1)			10	μA
I_P	Peak Current *	see Figure 3 (Gate)	0.3			A

* Applicable to both forward and reverse directions.

** Connected in parallel with the devices.

DIAC

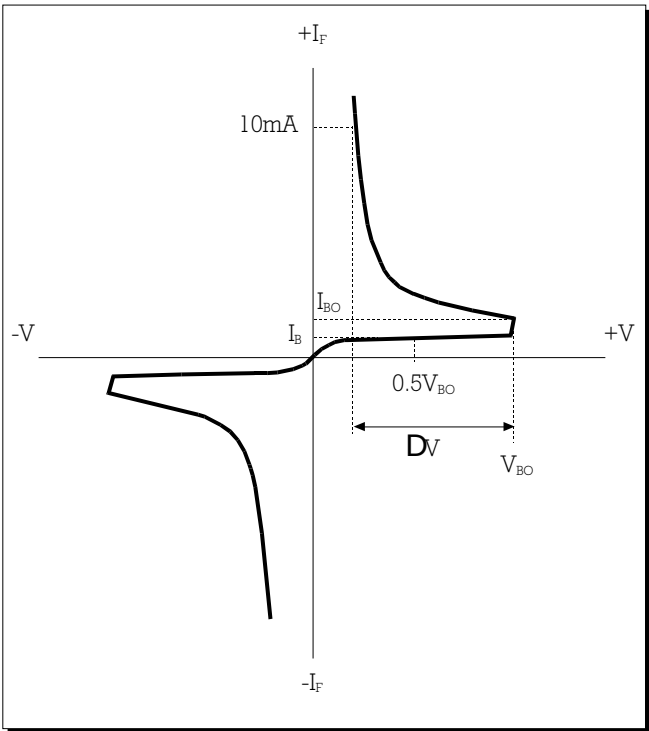


FIGURE 1: Current-Voltage Characteristics

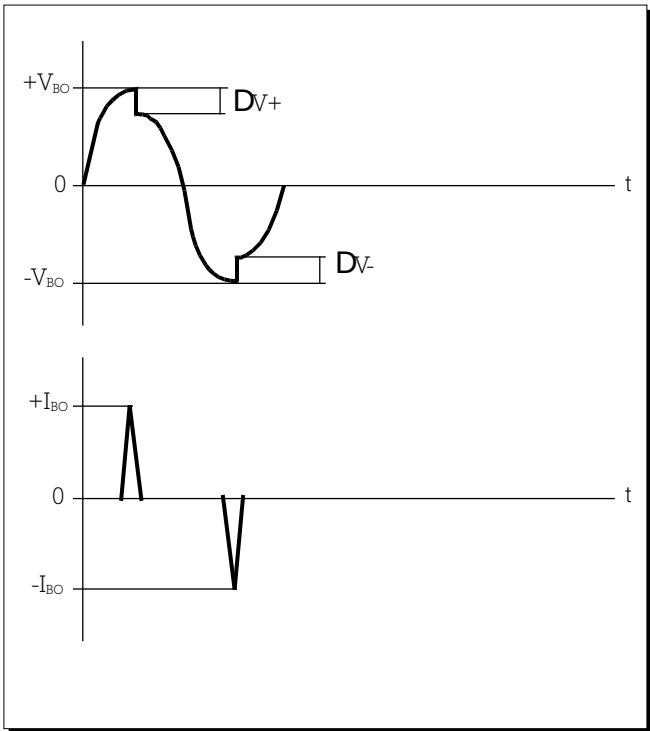


FIGURE 2

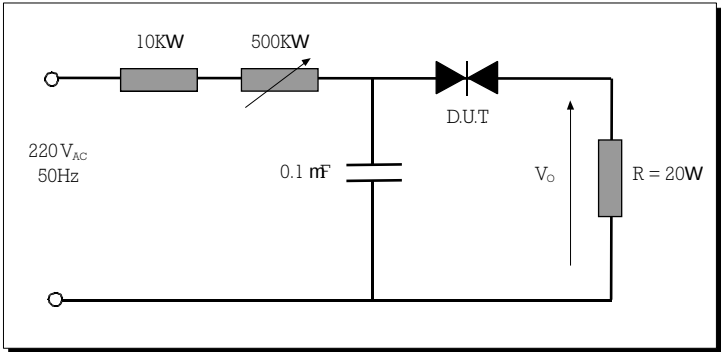


FIGURE 3: Test Circuit for Output Voltage.

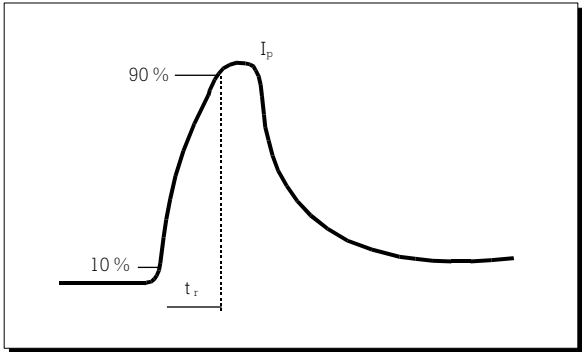


FIGURE 4: Test circuit see Figure 3. Adjust R for $I_p = 0.5\text{ A}$

PART NUMBER INFORMATION

